

# **Product Specification For TFT MODULE**

Model NO.: CNKT0700-21375A1

**CUSTOMER NO.:** 

**REVISION: V00** 

#### **APPROVAL FOR SPECIFICATIONS AND SAMPLE**

	APPROVED BY	DATE
CUSTOMER APPROVAL		
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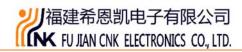
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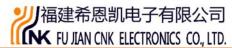


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Version	Date	Description
V00	2021/12/29	First released

PRODUCTOR No.: CNK0700-21375A1



1. Display Characteristics

Item	Specification	Unit	Note
LCD Size	7.0	inch	
Panel Type	IPS	-	
Resolution	280(RGB)(H)x1424(V)	pixel	
Display Mode	TRANSMISSIVE,NORMALLY BLACK	-	
Display Number of Colors	262K	-	
Viewing Direction	ALL VIEWING	-	Note1
Module Size	181.47*38.2*3.4	mm	Note1
Weight	TBD	g	
Driver IC	OTA7290B	-	
Interface	MIPI	_	

Note 1: Please refer to the mechanical drawing.

2. Pin Assignments

Pin No.	Symbol	Function	Note
1	VCOM	Common Voltage(3.7~6.86V, Typ:5.28V).	
2	VDD	Power Supply.	
3	VDD	Power Supply.	
4	NC	-	
5	RESET	Global reset pin	
6	STBYB	Standby mode. Normally pull high.	
7	GND	Power Ground	
8	D0-	MIPI data input	
9	D0+	MIPI data input	
10	GND	Power Ground	
11	D1-	MIPI data input	
12	D1+	MIPI data input	
13	GND	Power Ground	
14	D2-	MIPI data input	
15	D2+	MIPI data input	
16	GND	Power Ground	
17	CLK-	Clock input	
18	CLK+	Clock input	
19	GND	Power Ground	
20	D3-	MIPI data input	
21	D3+	MIPI data input	
22	GND	Power Ground	
23	NC	-	
24	NC	-	



25	GND	Power Ground
26	NC	-
27	NC	-
28	NC	-
29	AVDD	Power supply for analog circuits(11.38V).
30	GND	Power Ground
31	LEDK	backlight K-
32	LEDK	backlight K-
33	L/R	Source Right or Left sequence control.
34	U/D	Source Up or Down sequence control.
35	VGL	VGL voltage for GIP control circuit(-10.27V).
36	NC	
37	NC	
38	VGH	VGL voltage for GIP control circui(15.37V).
39	LEDA	Power for LED backlight (Anode)
40	LEDA	Power for LED backlight (Anode)

## 3. Absolute Maximum Ratings

Item	Symbol	Min	Max	Unit
Power supply	VDD	-	5.5	V
Operation temperature	Тор	-20	70	°C
Storage temperature	Tst	-30	80	°C

## 4. Electrical Characteristics

DC CHARACTERISTICS (at Ta=25°C)

Item	Symbol		Values			Note
itein	Symbol	Min.	Тур.	Max.	Unit	Note
Logic Supply Voltage	VDD	2.7	3.3	3.6	Vdc	
Supply Voltage For Panel	VGH	-	15.37	-	V	
	VGL	-	-10.27	-		
Input Logic High Voltage	ViH	0.8VDD	-	VDD	V	
Input Logic Low Voltage	VIL	0	-	0.2VDD	V	
Output Logic High Voltage	Vон	VDD-0.4	-		V	
Output Logic Low Voltage	Vol	GND	_	GND+0.4	V	



## 5. Backlight Characteristics

(at Ta=25°C,RH=60%)

Item	Symbol	Min.	Тур.	Max.	Unit	Note
LED forward voltage	VF	21.0	24.0	27.0	V	IF=1*20mA
LED forward current	IF		20		mA	
LED power consumption	PLED		-		mW	Note1
Uniformity		75	80		%	IF=20mA
Connection mode			8 series		/	
LED life-time		20000			Hrs	Note2

Note1.Calculator Value for reference: IF\*VF = PLED

Note2. The LED Life-time define as the estimated time to 50% degradation of initial brightness at Ta=25 $^{\circ}$ C and IF=180mA. The LED lifetime could be decreased if operating IF is larger than 180mA

**6. Optical Specifications** 

Item	Symbol	Condition	Min	Тур	Max	Unit	Note	
Response time	Ton+ Toff	Normal	-	30	40	ms	Note 4,5	
Contrast ratio	Cr	θ=Ф=0°		800	-	-	Note 1.5	
Surface luminance	Lv	θ=0°	TBD	TBD	-	cd/m^2	Note 2,5	
	θL	Left(CR>10)	-	80	-	deg		
Viewing angle	θR	Right(CR>10)	-	80	-	deg	Note 5,6	
range	θТ	Top(CR>10)	-	80	-	deg		
	θВ	Bottom(CR>10)	-	80	-	deg		
	Red x			0.644		-		
	Red y			0.332		_		
	Green x	θ=0°		0.324		-		
CIE (x, y)	Green y	Ø=0°	Тур	0.566	Тур	_	Note 3,5	
chromaticity	Blue x	©=0° Ta=25℃	-0.03	0.137	+0.03	-	INOIG 3,3	
	Blue y			0.125		-		
	White x			0.319		-		
	White y			0.343		-		

Note1.Definition of contrast ratio

Contrast Ratio(CR) is defined mathematically by the following formula.

Contrast Ratio = Average Surface Luminance with all white pixels Average Surface Luminance with all black pixels

Note 2. Definition of surface luminance

Surface luminance is the LCD surface from the surface with all pixels displaying white.

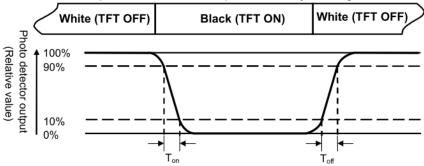
Lv = Average Surface Luminance with all white pixels

Note 3. Definition of color chromaticity (CIE1931)

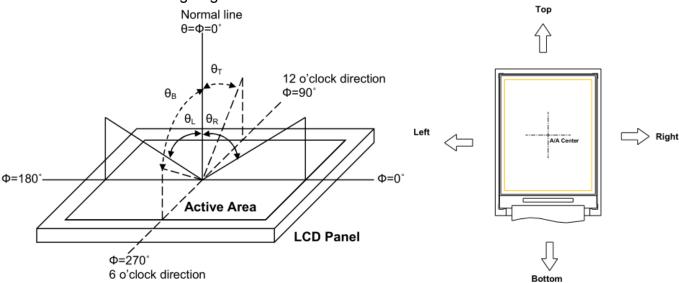
CIE (x, y) chromaticity ,The x,y value is determined by screen active area center position

#### Note 4: Definition of response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (T on ) is the time between photo detector output intensity changed from 90% to 10%, and fall time (T off) is the time between photo detector output intensity changed from 10% to 90%.



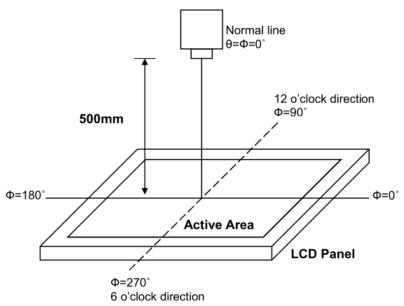
Note 5: Definition of viewing angle



Note 6: Definition of optical measurement system

The optical characteristics should be measured in a dark room with ambient temperature T a =+25. The optical properties are measured at the center point of the LCD screen after 5 minutes operation. (Equipment: Photo detector TOPCON BM-5A or BM-7 /Field of view: 1° /Height: 500mm.)

#### Photo detector



## 7. AC Characteristics

Refer to IC datasheet

## 8. Power sequence

Refer to IC datasheet

### 9. Reliability Test Conditions

Test item	Test condition	Inspection after test
High temperature storage	80±2°C/240 hours	
Low temperature storage	-30±2°C/240 hours	
High temperature operating	60±2°C/24hours	
Low temperature operating	-20±2°C/24 hours	
Temperature Shock	-20±2°C~25°C~70±2°C*10cycles (30min.) (5min.) (30min.)	
High Temperature Humidity Operation	60°C*90% RH/96 hours	Note 1,2
Vibration test	Frequency: 10Hz~55Hz~10Hz Amplitude: 1.5mm, X, Y, Z direction for total 2hours(Packing condition)	
Dropping test	Drop to the ground from 1m height, one time, every side of carton. (Packing condition)	



ESD fest	Voltage : ±8KV, R:330Ω /C:150pF	
	Air discharge, 10 time	

## 10. Handling Precautions

- 10.1. Safety
- 10.1.1.The liquid crystal in the LCD is poisonous.do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 10.2. Handling
- 10.2.1. The LCD and touch panel is made of plate glass.do not subject the panel to mechanical shock or to excessive force on its surface.
- 10.2.2.do not handle the product by holding the flexible pattern portion in order to assure the reliability
- 10.2.3. Transparency is an important factor for the touch panel. Please wear clear finger sacks, gloves and mask to protect the touch panel from finger print or stain and also hold the portion outside the view area when handling the touch panel.
- 10.2.4. Provide a space so that the panel does not come into contact with other components.
- 10.2.5. To protect the product from external force, put a covering lens (acrylic board or similar board) and keep an appropriate gap between them.
- 10.2.6. Transparent electrodes may be disconnected if the panel is used under environmental conditions where dew condensation occurs.
- 10.2.7. Property of semiconductor devices may be affected when they are exposed to light, possibly resulting in IC malfunctions.
- 10.2.8. To prevent such IC malfunctions, your design and mounting layout shall be done in the way that the IC is not exposed to light in actual use.
- 10.3. Static Electricity
- 10.3.1. Ground soldering iron tips, tools and testers when they are in operation.
- 10.3.2. Ground your body when handling the products.
- 10.3.3. Power on the LCD module before applying the voltage to the input terminals.
- 10.3.4.do not apply voltage which exceeds the absolute maximum rating.
- 10.3.5. Store the products in an anti-electrostatic bag or container.
- 10.4. Storage
- 10.4.1. Store the products in a dark place at +25°C±5°C with low humidity (65%RH or less).
- 10.4.2.do not store the products in an atmosphere containing organic solvents or corrosive gas.
- 10.5. Cleaning
- 10.5.1.do not wipe the touch panel with dry cloth, as it may cause scratch.
- 10.5.2. Wipe off the stain on the product by using soft cloth moistened with ethanol.do not allow ethanol to get in between the upper film and the bottom glass. It may cause peeling issue or defective operation.do not use any organic solvent or detergent other than ethanol.



## 11. Inspection Criterion

#### 1.1 Description

This specification is made to be used as the standard acceptance/rejection criteria for TFT LCM Product.

#### 11.1.1.Sample plan

Sampling plan according to GB/T2828.1-2003/ISO 2859-1: 1999 and ANSI/ASQC Z1.4-1993, normal level 2 and based on:

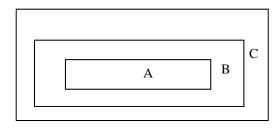
Major defect: AQL 0.65 Minor defect: AQL 1.5

#### 11.1.2. Inspection condition

- •Viewing distance for cosmetic inspection is about 30±5cm with bare eyes, and under an environment 600~1000lux for visual inspection and 0~200lux for function test., all directions for inspecting the sample should be within 45°against perpendicular line. (Normal temperature 18~28°C and normal humidity 60±15%RH).
- Driving voltage

The Vop value from which the most optical contrast can be obtained near the specified Vop in the specification (Within  $\pm 0.5$ V of the typical value at 25°C.).

#### 11.1.3. Definition of inspection zone in LCD



Zone A: character/Digit area

Zone B: viewing area except Zone A (Zone A+Zone B=minimum Viewing area)

Zone C: Outside viewing area (invisible area after assembly in customer's product)

Fig.1 Inspection zones in an LCD.

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product.

## 11.2 Inspection criterion

#### 11.2.1 Function defect

Items to be	Inapaction oritorian	Classification
inspected	Inspection criterion	of defects

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All functional defects	No display     Display abnormally     Missing vertical, horizontal segment     Short circuit     Back-light no lighting, flickering and abnormal lighting.     obvious striation     Current beyond specification value	MA
Missing	Missing component	
Outline dimension	Overall outline dimension exceed the drawing is not allowed.	

11.2.2 LCD pixel defect (bad dot) (defect type:MI)

THELE LOD PIXOT GOTOOT ( Dad Go	<del>t) (40.00t</del>	<i>'</i>	
Checking item		Judgment criterion	
Item/LCD size	S ≤5.0 Inch	5.0 < S≤7.0 Inch	7 < S≤12.3 Inch
Color bad dot-bright dot(R、G、B)	1	2	3
two adjacent bright point	0	1	2
three or more adjacent point	0	0	0
total points for bad dot-bright dot	1	2	5
Bad dot-dark dot	2	4	5
two adjacent dark point	1	2	3
three or more adjacent point	0	1	1
total points for bad dot -dark dot	3	6	7
patch bright dot		Invisible with ND5%, it is C	K.

11.2.3 dot and line defect (defect type:MI)

	and mic acid		, p • ,			
Chaoking	Judgment criterion					
Checking		a)\\ CD Siza	S ≤5.0	5 < S≤7	7 < S≤12.3	Figure
item	Diameter(mm	I)\LCD Size	Inch	Inch	Inch	
	D≤0.1		allowed	allowed	allowed	
	0.1 < D≤0.2		4	allowed	allowed	
Dot	0.2 < D≤0.3		0	5	•	\$ b
defect	0.3 < D≤0.5		0	0	6	a
	D > 0.5		0	0	0	D=(a+b)/2
	the distance	e between th	e two defec	t dot:DS≥5m	m	,
	Length(mm)	width(mm )	Jı	udgment crit	erion	
line	disregard	W≤0.05	allowed	allowed	allowed	<b>←</b> , →
defect	L≤5	0.05 <	4	5	7	1 w
	L≥O	W≤0.1	4	5	7	
	L>5	W > 0.1	0	0	0	



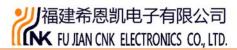
Concave	LCD Siz	ze(mm)	Jud	dgment cri	terion	
point and	D≤	0.3	allowed	allowed	allowed	
air bubble	0.3 < D≤1.0		3	4	5	\$ ь
for	1.0 <	D≤1.5	1	2	3	ГаЛ
polarizer	D>	1.5	0	0	0	D=(a+b)/2
	Length ( mm)	width ( mm)	Ju	ıdgment cr	iterion	
	disregard	W≤0.05	allowed	allowed	allowed	
Fold	1 < L≤5	0.05 < W≤0.2	3	4	5	L W
mark、 linear	L > 5	W > 0.2	0	0	0	<u> </u>
scar for polarizer	Notes:1.If the fold mark and linear scar for polarizer is visible with operation condition, the defect is judged with line judge; 2.If the fold mark and linear scar for polarizer visible with non-operating condition, the defect is judged with the above judgment standard.					r for polarizer is

11.2.4 Corner and others crack for LCD (defect type:MI)

Checking item	Judgment criterion	Figure
Electric conduction crack	X≤3.0mm,Y≤1/4w,Z≤t,N≤2	V J J J J Z
corner crack	X≤3.0mm,Y≤3.0mm , Z≤t,N≤3 Corner crack extended to ITO PIN,none allowed	
surface crack	X≤1.5mm,Y≤1.0mm, Z≤t, N≤4	Z A T

11.2.5 Module Cosmetic Criteria (defect type:MI)

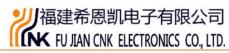
industry modulo contona (dolost typonin)			
Item	Judgment Criterion		
Difference in Spec.	None allowed		
Pattern peeling	No substrate pattern peeling and floating		
	No soldering missing		
Soldering defects	No soldering bridge		
	No cold soldering		



	Notes:detail judgment referring to IPC-A-610 grade II			
Resist flaw on Printed	visible copper foil ( 0.5mm or more) on substrate pattern, none			
Circuit Boards	allowed			
Accretion of metallic	No accretion of metallic foreign matters (Not exceed 0.2mm)			
Foreign matter				
Stain	No stain to spoil cosmetic badly			
Plate discoloring	No plate fading, rusting and discoloring			
Newton ring	Referring to limited sample			
Mura	Invisible with 5%ND,allowed			
Light leaks	Referring to limited sample			

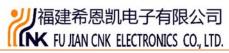
## 11.2.6 Module Cosmetic Criteria

Inopostion		Defect level		Inspection
Inspection	Inspection content	MAJ	MIN	Methods
items				and Tools
	The PIN cannot be broken.	<b>V</b>		
	Fold marks: Not in V" shape	$\checkmark$		
	Pin/line: concave, convex, skewed not to exceed		$\sqrt{}$	
	1/3 of width		V	
	Double-sided adhesive tape cannot fall off/skew		$\checkmark$	
	Oxidation on pins (PAD) is not allowed		$\checkmark$	
	open circuit /short circuit is not allowed on line	√		
	Line / line: non-conductive sundries must not			
	cross two lines, conductive sundries according to		$\sqrt{}$	Inspection
FPC	convex / concave judgment			with naked
segment	The PAD on the product do not warp, deform or		$\sqrt{}$	eyes
	fall off			Standard
	Scratch: Scratch is not allowed on the film		√	
	Cover film: the sticker offset must not exceed the		$\sqrt{}$	card
	drawing requirements		*	Magnifier
	Bubbles: Bubbles must not span 2 lines and must		$\sqrt{}$	
	not exceed 2	,	*	
	Stratification: product is not layered	√		
	Screen printing: screen printing should be clear,		$\sqrt{}$	
	not duplicate, missing or wrong		,	
	Guide pin indispensable/unbroken	,	√	
Back-light	No surface breakage/crack	√	<u>,                                      </u>	
	Reflex tape/ FPC not dropped		$\sqrt{}$	



	The double-sided glue on the light guide plate must not be removed		<b>√</b>	
	Solder not melted			
SMT	Component standing or solder joint and end face disengage	√		
segment	Tin beads: removable tin beads not available, non-removable tin beads not exceeding 0.2 MM in diameter		V	
	Line 1. Broken circuit or short circuit not allowed 2.Line damage or residual copper no more than 1/3 W	V		
	Scratch on the surface 1. scratch copper, reject 2. copper single line (not covered with green paint)>1 mm, reject 3. No more than 2 lines and exposed copper		<b>V</b>	
SMT segment	Part error 1. Part specification, material number failed to match original part data ,reject 2. missing /multiple parts: no missing or multiple parts on the circuit board 3. reverse: no positive and negative wrong welding of parts on circuit board	$\sqrt{}$		Visual Standard card Magnifier
	Tin on board 1.Tin in front of 1/2 Lead, reject 2. products have hot pressing process, its gold finger (pressing area) tin, reject		<b>V</b>	
	Empty welding: welding surface and pad are not joint	<b>√</b>		
	No tin tip / crack or virtual welding		√	
	No white powder residue		√	

	Component offset		
	1.B≥1/2≥•L 2.A ≥2/3•W		
	A W	V	
	3.A≥ 2/3•W B≥ 1/2•L 4.t≥ 1/2*T  Reference 1,2  T		
	Solder height is higher than solder foot 1.25 H( gull airfoil), reject		
SMT segment	Solder height is higher than surface (round type), reject	$\checkmark$	Visual Standard card Magnifier



	Gull airfoil: Solder height less than solder foot 1/3			
	H, or the solder pad less than 70% tin, reject			
	<1/3 H NG			
	Cylindrical type: solder height less than surface 1/4 H or the solder pad less than 70% tin, reject	$\sqrt{}$		
	<1/4 H NG			
	<70% NG			
	Connectors (including: card cover) are not broken or dropped	√		
	Board warping: the gap between the PCB and the plane is not greater than 1/100 of the length (if no special requirements, according to this standard)		√	
Other	SI/UV adhesive coating must not have obvious concave and convex		<b>√</b>	Visual Magnifier
	SI/UV glue not coated/ dropped or not fit in size		√	
	No glue in non-coating areas		<b>√</b>	
	Print position / font / text not in accordance with requirements		√	
	Easy to tear film color / position not in accordance with requirements		<b>V</b>	
Incoming, process, ROSH process control, check for conformity		$\sqrt{}$		
Packaging and marking of the product are clear and correspond to the report		V		Visual



The relevant information provided to the customer is complete	ما	
When the customer has a request	٧	

## 11.2.7 structure, packaging inspection:

Inspection	Inspection criterion	Defect level		Inspection Methods
items		MAJ	MIN	and Tools
Structure	The structure does not conform to the drawing	V		
segment	size	\ 		
	Packaging material compliance	V		
	Packing Type Compliance	$\sqrt{}$		
	Tray or not	$\sqrt{}$		
	Packing Quantity Compliance	$\sqrt{}$		Visual
Packing	Product packaging (placement) direction meets	√		
	the requirements			
	Cartons damaged/deformed		√	
	Labels are required on inner/external packing	√		
	cases (content: model, date, etc)			

#### Remarks:

- 1. above all structural dimensions per batch sampling quantity of 10 PCS, bad is not qualified.
- 2. environmental protection requirements:product inspection
- 2.1 Incoming, process, ROSH process control, check for conformity;
- 2.2 Packaging and marking of the product are clear and correspond to the report
- 2.3 The relevant information provided to the customer is complete When the customer has a request

## 12. Mechanical Drawing

